

Customer Information Notification

202502010I: Datasheet Update for CAN SIC Products TJA1462 and TJA1463

Note: This notice is NXP Company

Proprietary.

Issue Date: Feb 14, 2025 Effective Date: Mar 14, 2025

Here is your personalized communication about an NXP notification. For detailed information we invite you to view this notification online

Management summary

Datasheet Update for CAN SIC Products TJA1462 and TJA1463

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[X]Electrical spec./Test coverage
[]Firmware [X]Other: Datasheet update				

Notification Overview

Description

NXP Product Line In-Vehicle Networking (PL IVN) is updating the datasheets of CAN SIC (Signal Improvement Capability) products TJA462 and TJA1463. The two primary improvements are:

- Compliance to the new ISO 11898-2:2024 standard, and associated reformatting of

timing characteristics

- Addition of SAE J2962-2:2019 ESD specifications

On request a product PPAP is available with an updated C&S ISO compliance and an additional SAE ESD report, both of which are provided by external test houses. This is why above electrical spec./Test coverage has been marked. Note that no change has been made to the NXP test programs.

Note that no change has been made to the products, this is purely a datasheet update. The datasheets revision history specifies all the updates.

Attached to this Customer Information Notification (CIN) are five additional documents:

- A pdf document with detailed information on the datasheet updates
- The ZVEI Delta Qualification Matrix (DeQuMa) for these datasheet updates, both in zipped excel and pdf format. The applicable change ID numbers are SEM-DS-02 and SEM-DS-03
- The new TJA1462 datasheet
- The new TJA1463 datasheet

The new datasheets will also be published on the NXP website (<u>www.NXP.com</u>) one month after the distribution of this CIN to customers.

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents.

Reason

NXP PL IVN wants to properly inform you of the improved datasheet specifications for the TJA1462 and TJA1463 products.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on specification, form, fit, function(ality), performance, reliability or quality, with the exception of the intended specification improvements

Data Sheet Revision

A new data sheet will be issued

Additional information

Additional documents: view online

Remarks

As direct recipient of this NXP PL IVN CIN, please use the 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files'. If you're not the original recipient, i.e. this CIN has been forwarded to you, you should contact the original recipient(s) within your company or your distribution supplier to obtain the attachments.

Note that this is a Customer Information Notification (CIN), not a PCN. We're informing you of a datasheet change, leading to improved and additional specifications, not asking nor waiting for your approval. A PPAP with the updated C&S report and the additional SAE ESD report is available on request, and can only be obtained by your (local) NXP sales contact(s) for you.

Should you, after having read both CIN and its attachment with detailed explanation, still have questions, please contact us via below e-mail address.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Kees van Hasselt

Position Quality Account Manager

e-mail

ivn.customer.service@nxp.com

address

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

NXP Semiconductors High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2025 NXP Semiconductors. All rights reserved.